

Approval sheet

Customer: _____

Model name: JT350MTVHV01

Spec NO: _____

Date: 2017.10.19

Version: 04

- Preliminary Specification**
- Final Specification**

For Customer's Acceptance

Approved by	Content

Approved by	Reviewed by	Prepared by

Records of Revision

DATE	REF.PAGE PARAGRAPH DRAWING No.	REVISED No.	SUMMARY	REMARK
2016-12-13		V01	First Issue	
2017-7-29		V02	Modify the block	
2017-9-5		V03	Update surface luminance	
2017-10-19		V04	Correct Interface Pin Function	

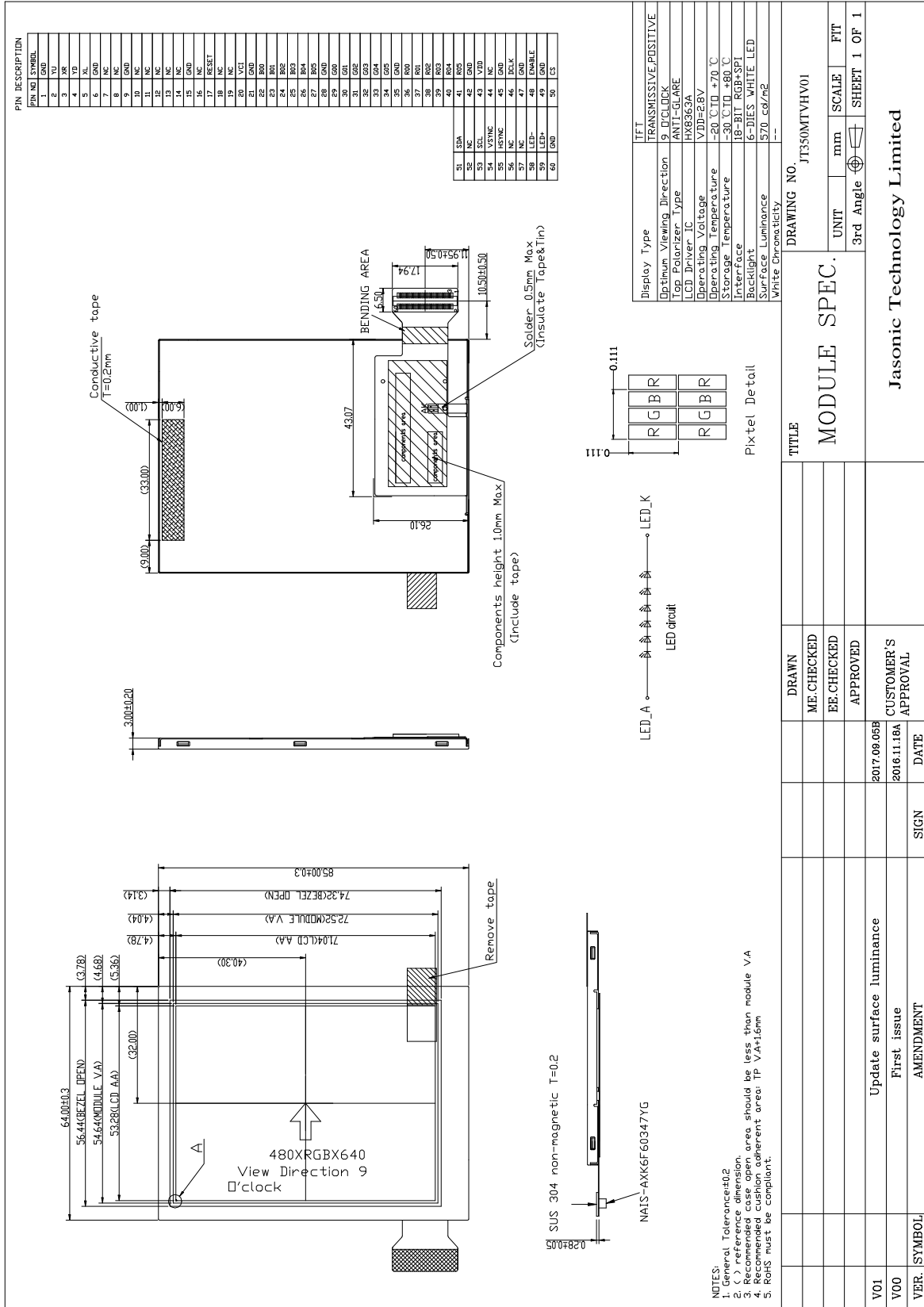
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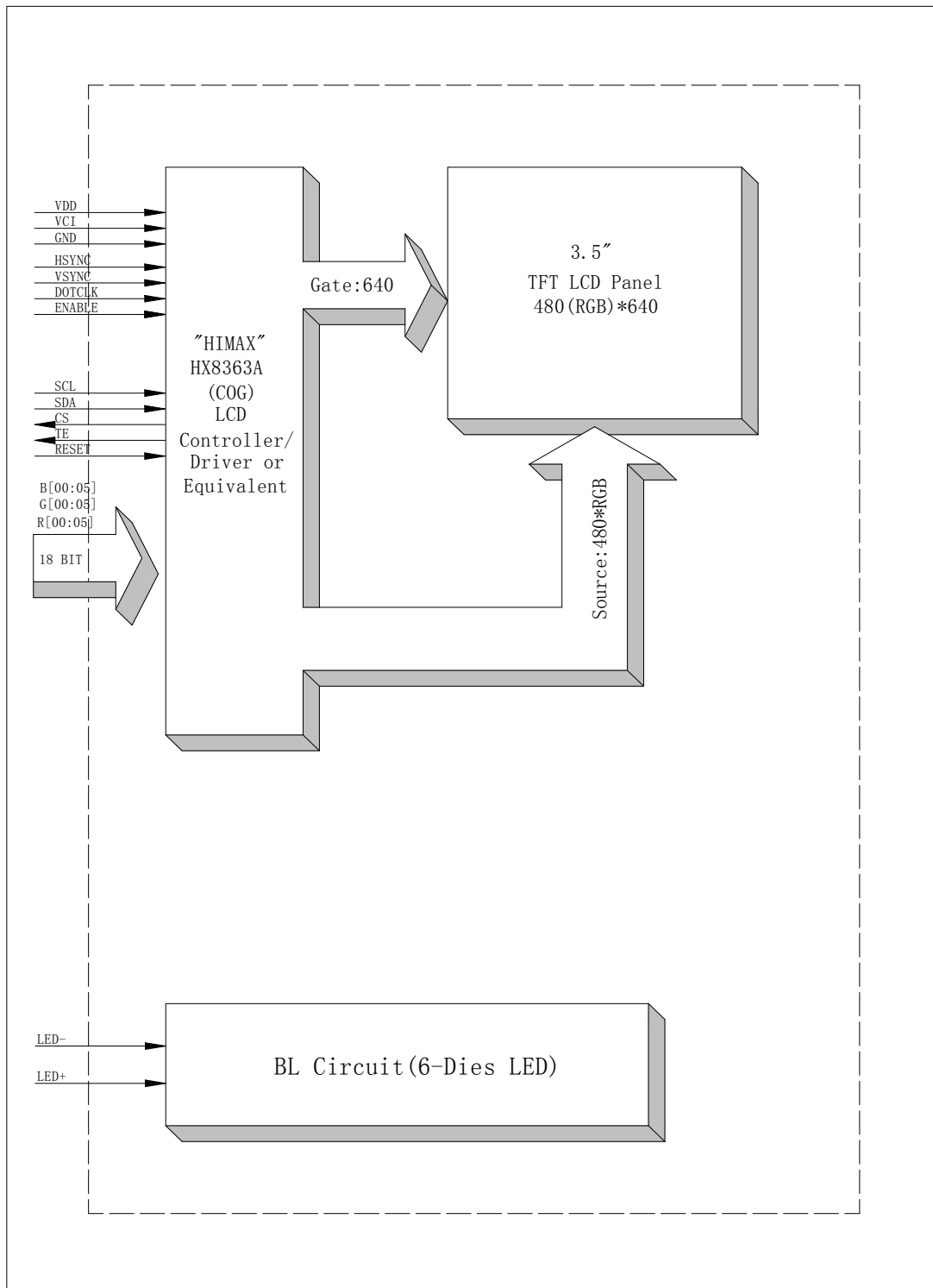
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	64.0*85.0*3.0	MM
ACTIVE SIZE (W*H)	53.28*71.04	MM
PIXEL PITCH (W*H)	0.111*0.111	MM
NUMBER OF DOTS	480*640	
DIVER IC	HX8363A	
INTERFACE TYPE	SPI+18BIT RGB	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	9	O'CLOCK
GRAY SCALE INVERSION DIRECTION	3	O'CLOCK
COLORS	262K	
BACKLIGHT TYPE	6-DIES WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

2. Mechanical Drawing



3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description
1	GND	Power ground.
2	YU	TP Pin.
3	XR	TP Pin.
4	YD	TP Pin.
5	XL	TP Pin.
6	GND	Power ground.
7	NC	No connect
8	NC	No connect
9	GND	Power ground.
10-14	NC	No connect
15	GND	Power ground.
16	NC	No connect
17	RESET	RESET PIN
18~19	NC	No connect
20	VCI	Power supply for logic
21	GND	Power ground.
22~27	B00~B05	Blue Data bus.
28	GND	Power ground
29~34	G00~G05	Green data bus
35	GND	Power ground
36~41	R00~R05	Red data bus
42	GND	Power ground
43	VDD	Power supply for analog
44	NC	No connect
45	GND	Power ground
46	DCLK	Pixel clock signal
47	GND	Power ground
48	ENABLE	Display data enable signal
49	GND	Power ground
50	CS	Chip select
51	SDA	Serial data signal input/out
52	NC	No connect
53	SCL	Serial clock signal
54	VSYNC	Vertical signal YNC
55	HSYNC	Horizon signal YNC
56~57	NC	No connect
58	LED-	Cathode of backlight
59	LED+	Anode of backlight
60	GND	Power ground

5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VDD	-0.3	4.6	V
Supply voltage for logic	VCI	-0.3	4.6	V
Supply current (One LED)	I _{LED}		30	mA
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Typ.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VDD	2.5	2.8	3.3	V	
Supply Voltage for Logic	VCI	1.65	1.8/2.8	3.3	V	
Input Voltage	V _{IL}	GND	-	0.3VCI	V	
	V _{IH}	0.8 VCI	-	VCI		
Input leakage Current	I _{LKG}	-1		1	μA	

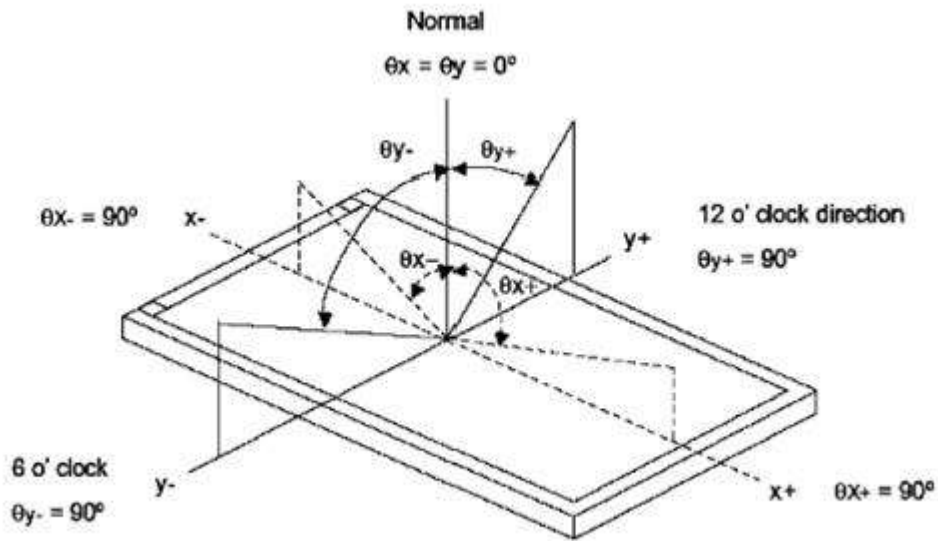
6.2 Backlight Driving Conditions

Item	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Voltage for LED Backlight	V _F	18.0	19.2	20.4	V	I _L =20mA
Current for LED Backlight	I _L		20	30	mA	
Power Consumption	P		0.384		W	
LED Life Time		30,000			Hr	Note

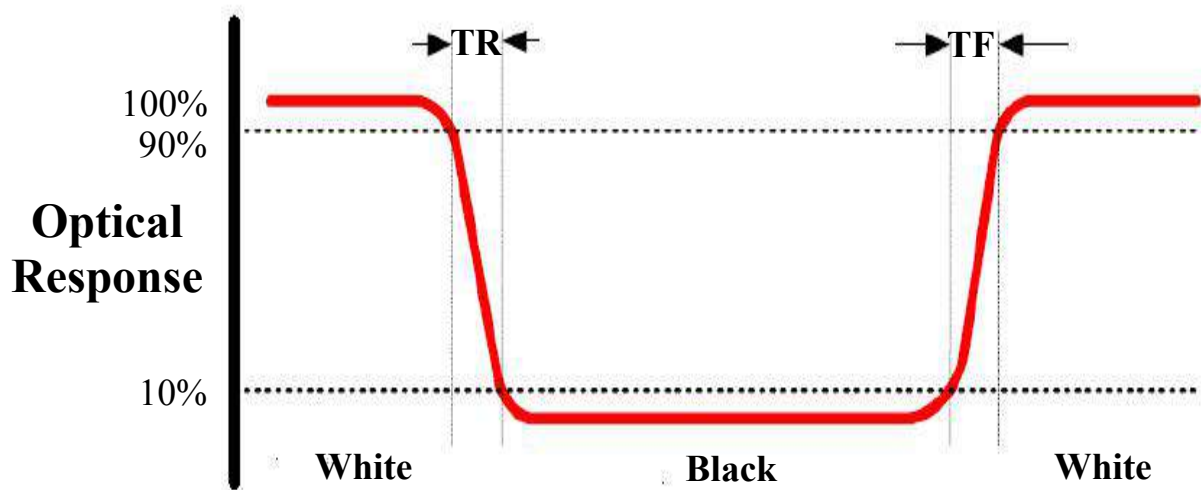
Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25°C

7. Optical Characteristics

ITEM	SYMBOL	CONDITIONS	SPECIFICATIONS			UNIT	NOTE
			MIN	TYP.	MAX		
Luminance	L	$I_L = 20\text{mA}$	460	570	680	Cd/m^2	
Contrast Ratio	CR	$\theta = 0^\circ$	400	500			
Response Time	T_{ON}	25°C		25	35	ms	
	T_{OFF}						
CIE Color Coordinate	Red	X_R					
		Y_R					
	Green	X_G					
		Y_G					
	Blue	X_B					
		Y_B					
	White	X_W		0.293	0.313	0.333	
		Y_W		0.337	0.357	0.377	
Viewing Angle	Hor.	θ_{X+}		70		Degree	
		θ_{X-}		60			
	Ver.	θ_{Y+}		70			
		θ_{Y-}		70			
Uniformity	Un		80			%	

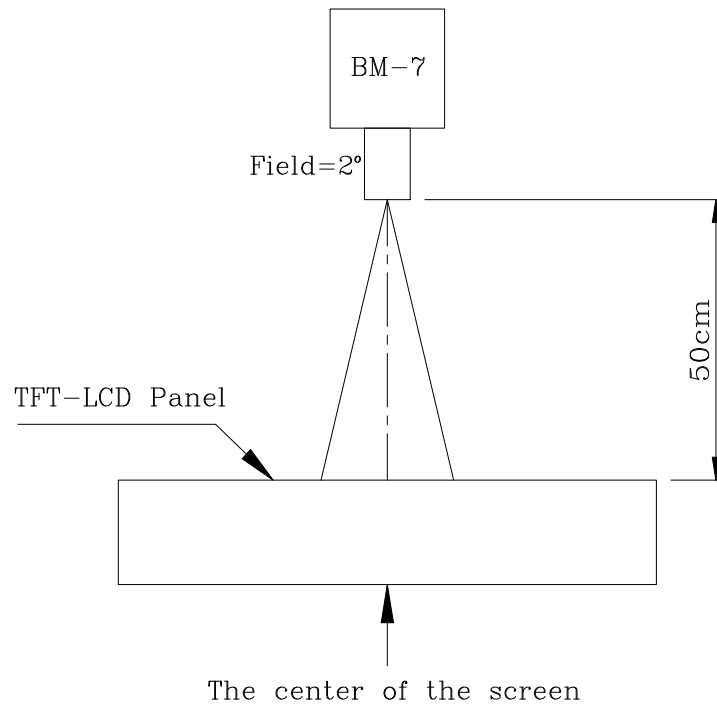
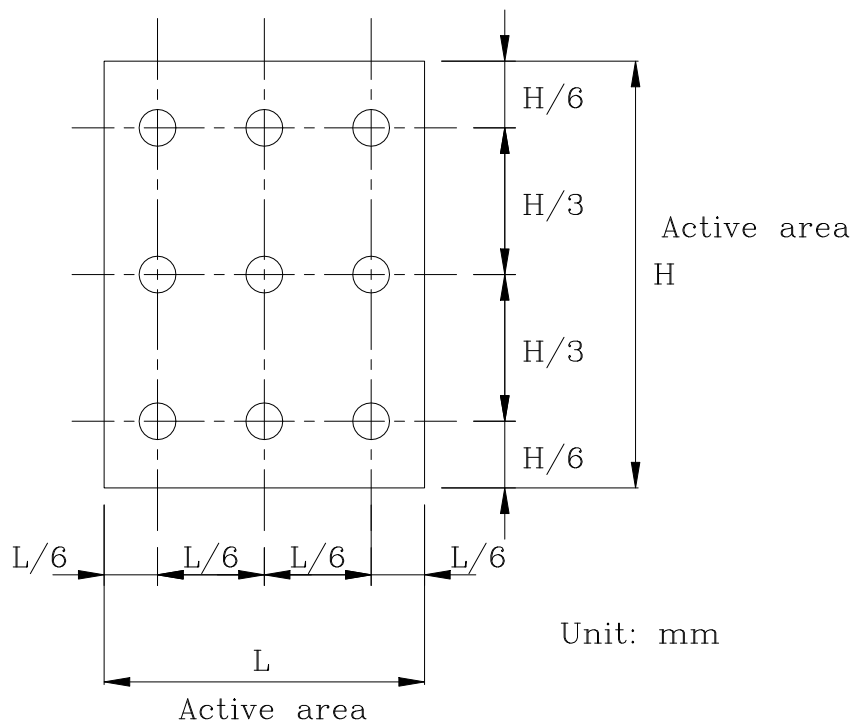
Note 1: Definition of Viewing Angle θ_x and θ_y :**Note 2: Definition of contrast ratio CR:**

$$CR = \frac{\text{Luminance of white state}}{\text{Luminance of black state}}$$

Note 3: Definition of Response Time (T_r, T_f)

Note 4: Definition of Luminance**①The Brightness Test Equipment Setup**

Field=2° (As measuring “black” image, field=2° is the best testing condition)

**②The Brightness Test Point Setup**

8. Timing Characteristics

8.1 SPI interface characteristics

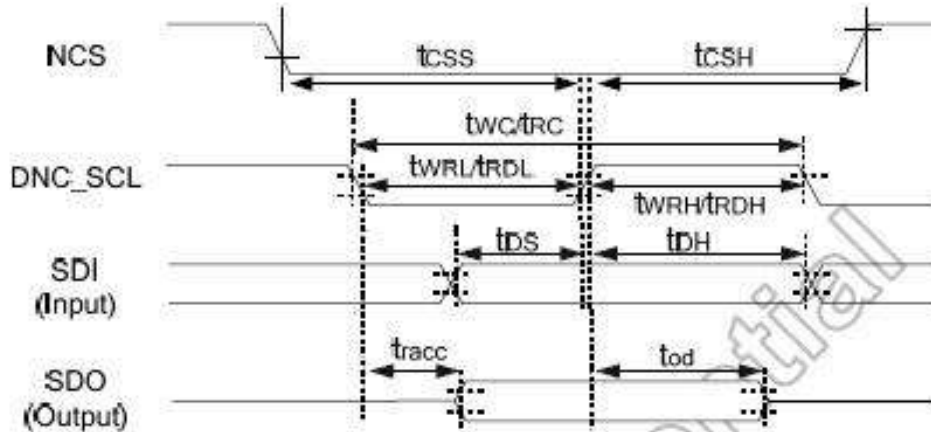


Figure 8.2: DBI Type C interface characteristics

(VSSA=0V, VDD1=1.8V, VDD2=2.8V, VDD3=2.8V, T_A = 25°C)

Signal	Symbol	Parameter	Min.	Max.	Unit	Description
NCS	t _{css}	Chip select setup time (Write)	15	-	ns	-
	t _{csh}	Chip select setup time (Read)	15	-	ns	
DNC_SCL (Write)	t _{wc}	Write cycle	80	-	ns	-
	t _{wRH}	Control pulse "H" duration	30	-		
	t _{wRL}	Control pulse "L" duration	30	-		
DNC_SCL (Read)	t _{rc}	Read cycle	150	-	ns	-
	t _{rDH}	Control pulse "H" duration	60	-		
	t _{rDL}	Control pulse "L" duration	60	-		
SDI (Input)	t _{DS}	Data setup time	10	-	ns	For maximum C _L =30pF For minimum C _L =8pF
	t _{DH}	Data hold time	10	-		
SDO (Output)	t _{racc}	Read access time	10	60	ns	
	t _{od}	Output disable time	15	100		

Note: The input signal rise time and fall time (tr, tf) is specified at 15 ns or less.

Logic high and low levels are specified as 30% and 70% of VDD1 for input signals.

Table 8.4: DBI Type C interface characteristics

8.2 RGB interface characteristics

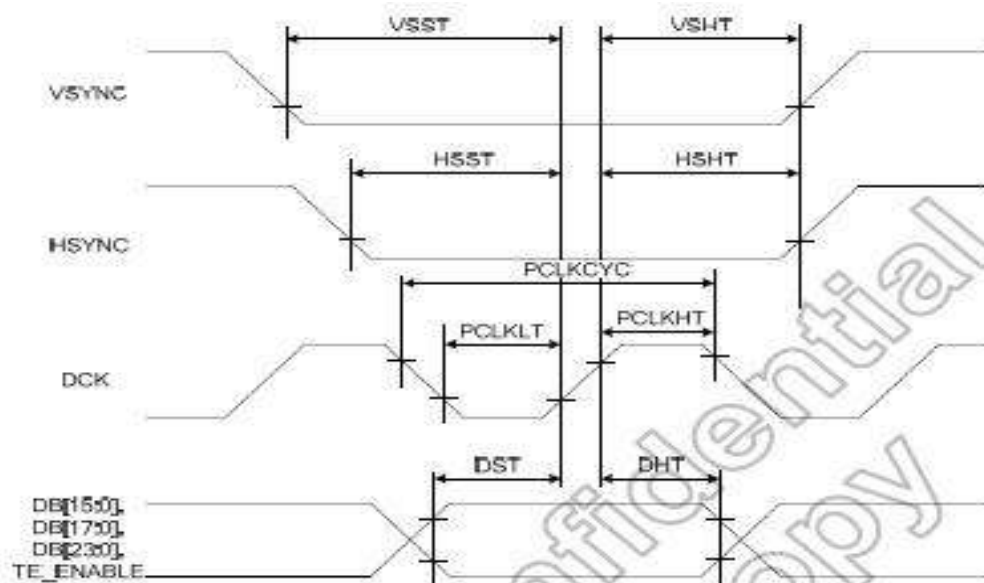


Figure 8.3: DPI interface characteristics

Resolution=480x854 (VSSA=0V, VDD1=1.8V, VDD2=2.8V, VDD3=2.8V, T_A=25°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Vertical sync. Setup time	VSST	-	10	-	-	ns
Vertical sync. Hold time	VSHT	-	10	-	-	ns
Horizontal sync. Setup time	HSST	-	10	-	-	ns
Horizontal sync. Hold time	HSHT	-	10	-	-	ns
Pixel clock cycle When RGB I/F is running	DCKCYC	VRR ⁽⁵⁾ = Min. 50 Hz Max. 70 Hz	29.1 (Note 3)	-	46.2 (Note 4)	ns
Pixel clock low time	DCKLT	-	10	-	-	ns
Pixel clock high time	DCKHT	-	10	-	-	ns
Data setup time DB[23:0]	DST	-	10	-	-	ns
Data Hold time DB[23:0]	DHT	-	10	-	-	ns

Note: (1) Signal rise and fall times are equal to or less than 20 ns.

(2) Input signals are measured by 0.30 x VDD1 for low state and 0.70 x VDD1 for high state.

(3) 34.3 MHz

(4) 21.6 MHz

(5) VRR : Vertical Refresh Rate, equal to VSYNC frequency.

9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30°C for 30 minutes → normal temperature for 5 minutes → +80°C for 30 minutes → normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ASTM-D-5327.
09	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times
		Contact: ±2KV 150pF/330Ω 5 time

*Sample size for each test item is 3~5pcs

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm 5^{\circ}\text{C}$), normal humidity ($50\pm 10\%$ RH), and in area not exposed to direct sun light.
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10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Us.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:
Major defect: AQL = 0.65
Minor defect: AQL = 2.5
Total defects: AQL = 2.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

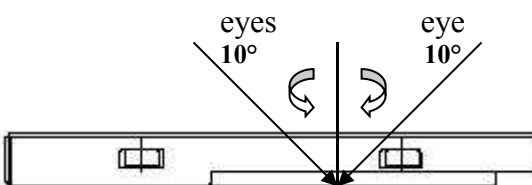
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

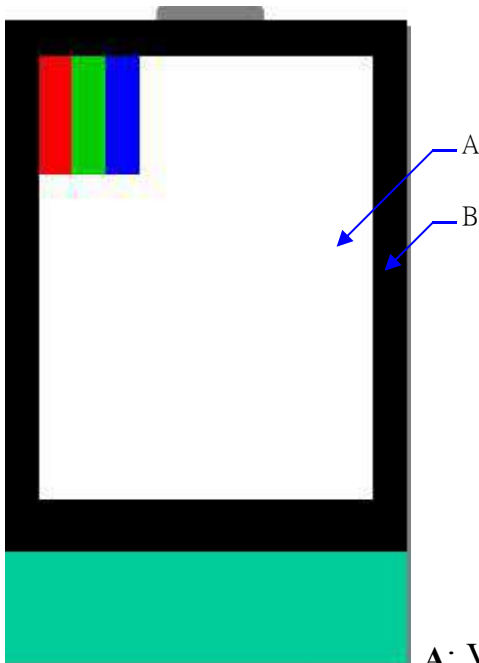
10.5 Standard of The Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



- Definition of area:

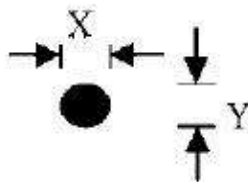
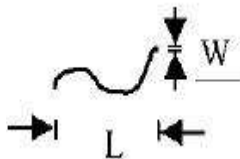


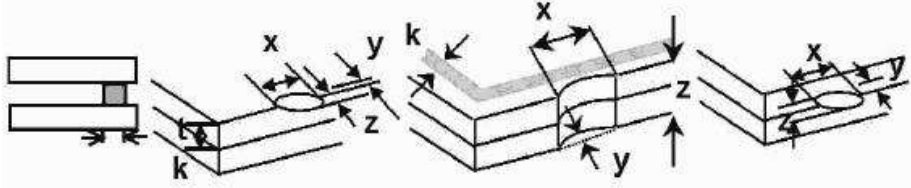
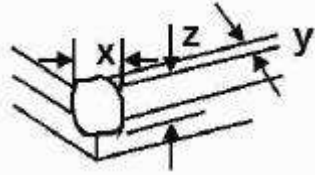
A: Viewing area B: Outside viewing area

10.5.2 Basic principle

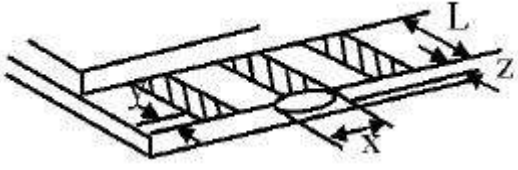
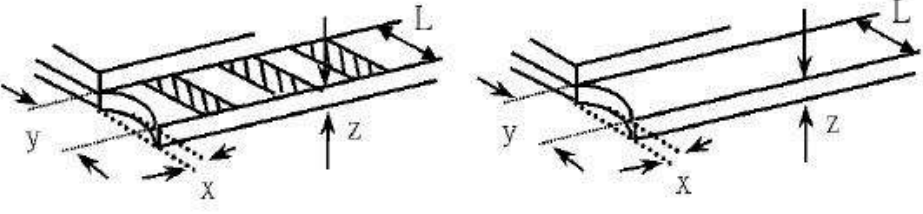
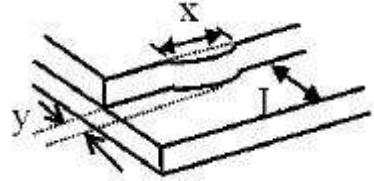
- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

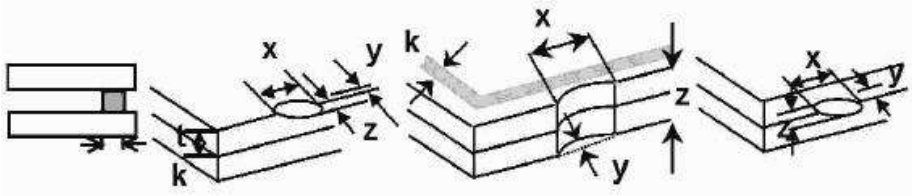
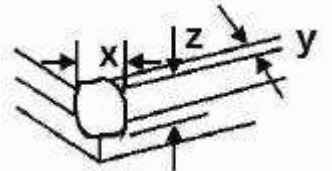
10.6 Inspection Specification

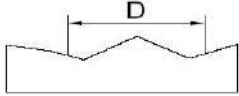
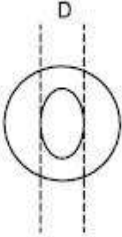
NO.	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker	0.65												
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or color spots on display $\leq 0.25\text{mm}$, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm.	2.5												
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As following drawing $\Phi = (X+Y) / 2$  <table border="1" data-bbox="821 1086 1353 1339"> <thead> <tr> <th>Size(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.10$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.10 < \Phi \leq 0.20$</td> <td>2</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.25$</td> <td>2</td> </tr> <tr> <td>$0.25 < \Phi \leq 0.30$</td> <td>1</td> </tr> <tr> <td>$0.30 < \Phi$</td> <td>0</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two spots within 3mm.</p>	Size(mm)	Acceptable Q'ty	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	2	$0.25 < \Phi \leq 0.30$	1	$0.30 < \Phi$	0	2.5
		Size(mm)	Acceptable Q'ty												
$\Phi \leq 0.10$	Accept no dense														
$0.10 < \Phi \leq 0.20$	2														
$0.20 < \Phi \leq 0.25$	2														
$0.25 < \Phi \leq 0.30$	1														
$0.30 < \Phi$	0														
3.2 Line type: (As following drawing)  <table border="1" data-bbox="726 1489 1353 1765"> <thead> <tr> <th>Length(mm)</th> <th>Width(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> </tr> <tr> <td>$L \leq 3.0$</td> <td>$0.02 < W \leq 0.05$</td> <td rowspan="2">2</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.08$</td> </tr> <tr> <td>---</td> <td>$0.08 < W$</td> <td>Rejection</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two lines within 3mm.</p>	Length(mm)	Width(mm)	Acceptable Q'ty	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.05$	2	$L \leq 2.5$	$0.03 < W \leq 0.08$	---	$0.08 < W$	Rejection	2.5
Length(mm)	Width(mm)	Acceptable Q'ty													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.05$	2													
$L \leq 2.5$	$0.03 < W \leq 0.08$														
---	$0.08 < W$	Rejection													

NO.	Item	Criterion			AQL	
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size Φ (mm)	Acceptable Q'ty	2.5	
			$\Phi \leq 0.20$	Accept no dense		
			$0.20 < \Phi \leq 0.50$	3		
			$0.50 < \Phi \leq 1.00$	2		
			$1.00 < \Phi$	0		
			Total Q'ty	3		
05	Scratches	Follow NO.3 -2 Line Type.				
06	Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:				2.5
			z: Chip thickness	y: Chip width	x: Chip length	
			$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	
			$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	
			⊙ Unit: mm			
			⊙ If there are 2 or more chips, x is the total length of each chip			
6.1.2 Corner crack:						
						
z: Chip thickness	y: Chip width	x: Chip length				
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$				
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$				
⊙ Unit: mm						
⊙ If there are 2 or more chips, x is the total length of each chip						

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	2.5 2.5 2.5 2.5 0.65 0.65
12	FPC	12.1 FPC terminal damage \cong 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage \cong 1/2 alignment area and can not affect the function , we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	2.5 0.65

NO.	Item	Criterion	AQL																
07	Glass crack	<p>Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length</p> <p>7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:</p>  <table border="1" data-bbox="558 784 1236 929"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>7.2.2 Non-conductive portion:</p>  <table border="1" data-bbox="558 1299 1236 1444"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged.</p> <p>7.2.3 Substrate protuberance and internal crack</p>  <table border="1" data-bbox="885 1769 1324 1915"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$X \leq a$</td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$X \leq a$	2.5
y: Chip width	x: Chip length	z: Chip thickness																	
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y: width	x: length																		
$y \leq 1/3L$	$X \leq a$																		

NO.	Item	Criterion	AQL												
14	Touch Panel Chipped glass	<p>Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length</p> <p>14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="451 792 1270 1010"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$Z \leq t$</td> <td>$\leq 1/2 k$ and not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip</p> <p>14.1.2 Corner crack:</p>  <table border="1" data-bbox="451 1386 1270 1603"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$z \leq t$</td> <td>$\leq 1/2 k$ and not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length													
$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$													
z: Chip thickness	y: Chip width	x: Chip length													
$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$													

NO.	Item	Criterion	AQL										
15	Touch Panel(Fish eye、dent and bubble on film)	<table border="1" data-bbox="456 371 989 577"> <thead> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.2$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.2 < D \leq 0.4$</td> <td>5</td> </tr> <tr> <td>$0.4 < D \leq 0.5$</td> <td>2</td> </tr> <tr> <td>$0.5 < D$</td> <td>0</td> </tr> </tbody> </table>  	SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.4$	5	$0.4 < D \leq 0.5$	2	$0.5 < D$	0	2.5
SIZE(mm)	Acceptable Q'ty												
$\Phi \leq 0.2$	Accept no dense												
$0.2 < D \leq 0.4$	5												
$0.4 < D \leq 0.5$	2												
$0.5 < D$	0												
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$) , it is acceptable.	2.5										
17	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5										
18	LCD Ripple	Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5										
19	General appearance	19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet.	0.65 0.65 0.65 0.65										

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of $25\pm 10^{\circ}\text{C}$, and in a relative humidity of $50\pm 10\%\text{RH}$. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than $280\pm 10^{\circ}\text{C}$ and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

12. Packing Method

----TBD